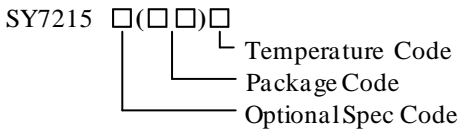


General Description

SY7215A develops a high efficiency synchronous Boost regulator with programmable output current limit. The IC adopts adaptive constant OFF time and current mode control. The integrated low $R_{DS(ON)}$ switches minimize the conduction loss.

SY7215A features cycle by cycle peak current limit, output short circuit protection and true shutdown. The IC also provides enable control and power good indicator for system sequence control. Low output voltage ripple and small external inductor and capacitor size are achieved with programmable pseudo-constant frequency.

Ordering Information



Ordering Number	Package type	Note
SY7215ARDC	QFN4×4-18	----

Features

- Input Range: 3-16V
- Programmable Pseudo-constant Frequency
- Low $R_{DS(ON)}$ Internal Switch
Main FET: 9mΩ
Rectified FET: 12mΩ
Disconnection FET: 12mΩ
- True Shutdown Function
- Programmable Output Current Limit
- Internal Soft-start Limits the Inrush Current
- Input Voltage UVLO
- Over Temperature Protection
- Over Voltage Protection
- Output Short Circuit Protection
- Minimum ON Time: 100ns typical
- Minimum OFF Time: 120ns typical
- RoHS Compliant and Halogen Free
- Compact Package: QFN4×4-18

Applications

- Power Bank
- High Power AP

Typical Applications

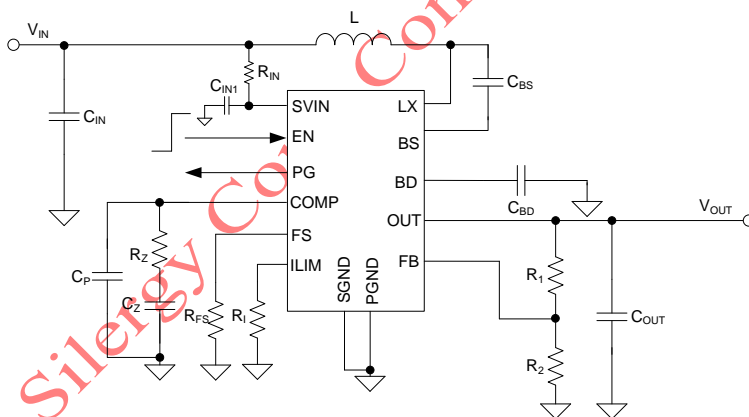


Figure1. Schematic Diagram

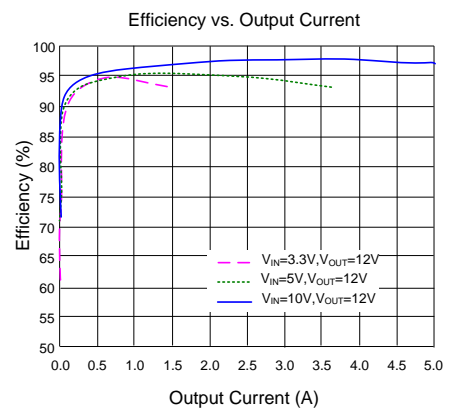
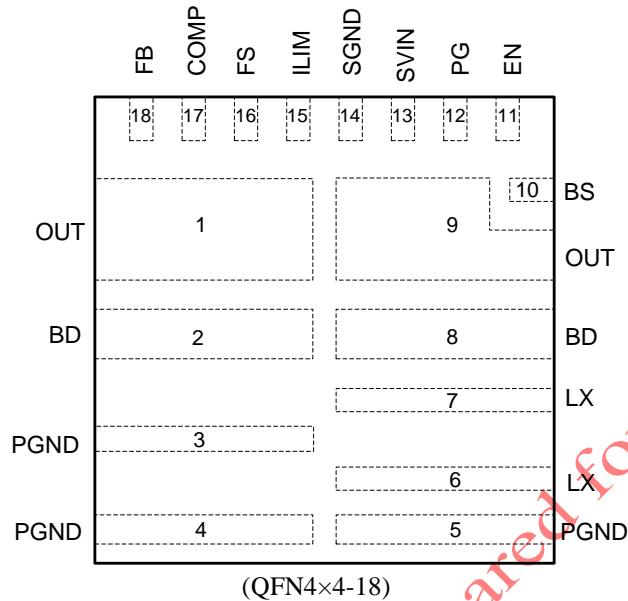


Figure2. Efficiency vs. Output Current

Pinout (top view)



Top mark: **BET**xyz (Device code: BET, x=year code, y=week code, z= lot number code)

Pin Name	QFN4x4-18	Pin Description
SVIN	13	IC power supply input pin. Decouple this pin to SGND pin with 1 μ F ceramic cap.
SGND	14	Signal ground pin.
PGND	3,4,5	Power ground pin.
LX	6,7	Inductor node. Connect an inductor from power input to LX pin.
FB	18	Feedback pin. Connected to the center of resistor voltage divider to program the output voltage: $V_{OUT}=1V \times (R1/R2+1)$
EN	11	Enable control. Pull high to turn on the IC. Do not leave it floating.
ILIM	15	Output current limit program pin. Connect a resistor R_{LIM} from this pin to SGND to program output current limitation threshold. $I_{LIM}(A)=15(V)/R_{LIM}(k\Omega)$
OUT	1,9	Boost converter output pin.
BD	2,8	Connected to the Drain of internal Disconnect FET. Bypass at least 4.7 μ F ceramic cap to PGND.
BS	10	Boot-strap pin. Supply rectified FET's gate driver. Decouple this pin to LX with 0.1 μ F ceramic cap.
FS	16	Switching frequency setting pin. Connect a resistor from this pin to ground to program the switching frequency. $F_{SW}(kHz)=1.4 \times 10^6 / R_{FS}(\Omega)^{0.645}$.
PG	12	Power good indicator. Open drain output, pull low when the output < 90% of regulation voltage, high impedance otherwise.
COMP	17	Loop compensation pin. Connect a RC network across this pin and ground to stabilize the control loop.

Block Diagram

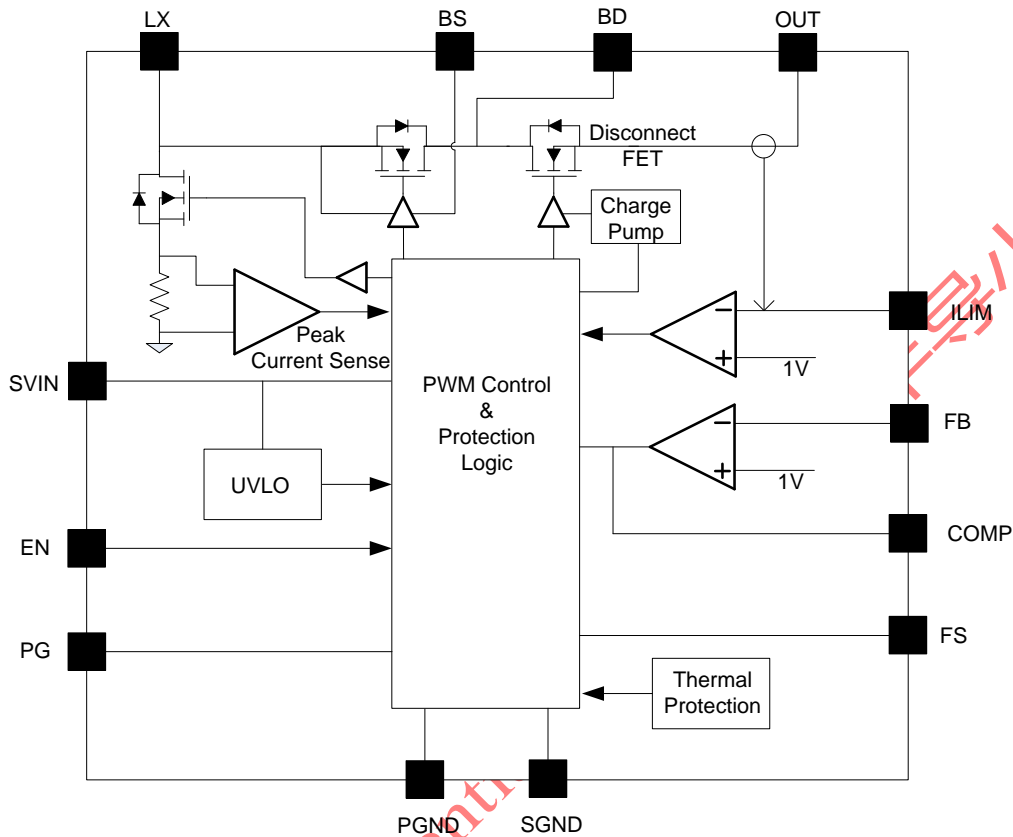


Figure3. Block Diagram

Absolute Maximum Ratings (Note 1)

SVIN, LX, EN, ILIM, OUT, BD, BS, FS, PG, COMP	-----	-0.3V to 18V
FB	-----	4V
BS-LX	-----	4V
Power Dissipation, Pd @ TA = 25°C QFN4×4-18	-----	3.4W
Package Thermal Resistance (Note 2)		
θJA	-----	30°C/W
θJC	-----	3.2°C/W
Junction Temperature Range	-----	-40°C to 125°C
Lead Temperature (Soldering, 10 sec.)	-----	260°C
Storage Temperature Range	-----	-65°C to 150°C

Recommended Operating Conditions (Note 3)

SVIN	-----	3V to 16V
Junction Temperature Range	-----	-40°C to 125°C
Ambient Temperature Range	-----	-40°C to 85°C

Electrical Characteristics

($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=100mA$, $T_A = 25^{\circ}C$ unless otherwise specified)

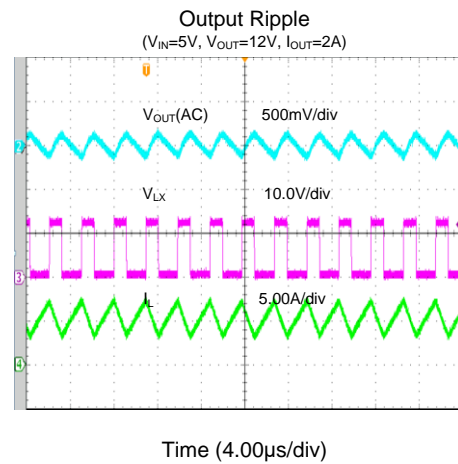
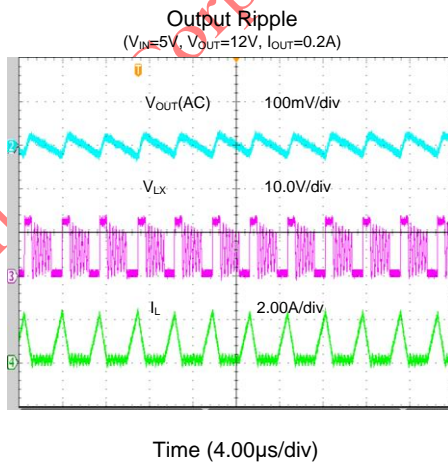
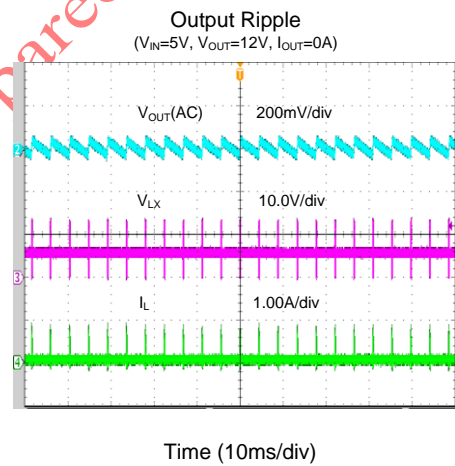
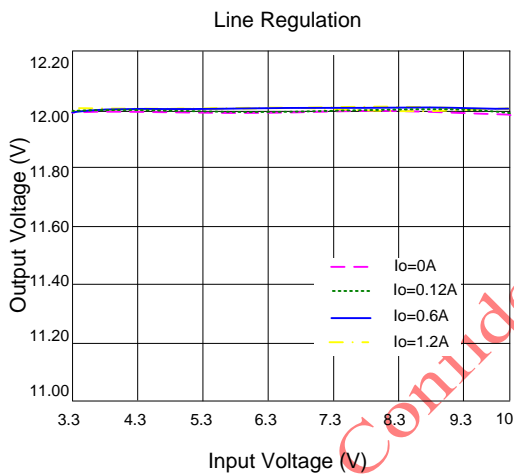
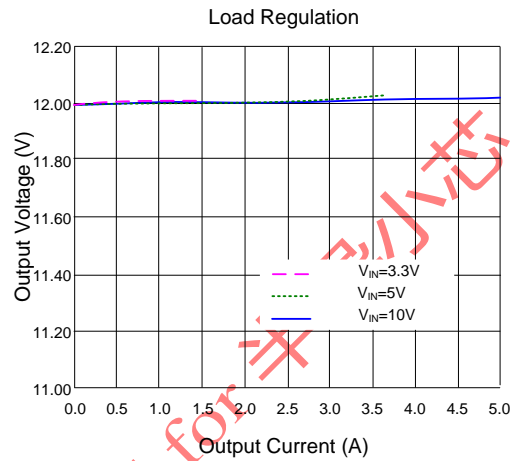
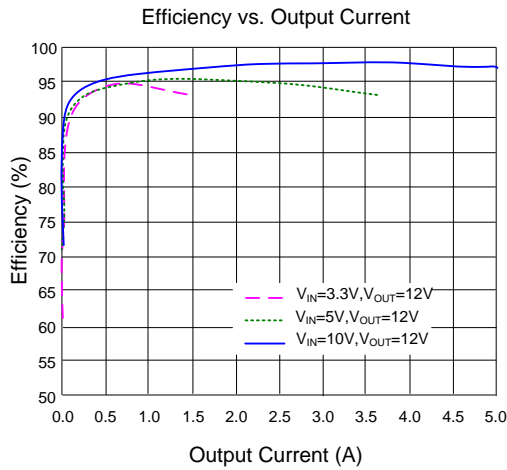
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage Range	V_{IN}		3		16	V
Output Voltage Range	V_{OUT}		$V_{IN} \times 1.1$		16	V
Output OVP Threshold	V_{FB_OVP}	V_{FB} Rising	110%	115%	120%	V_{REF}
Quiescent Current	I_Q	$V_{OUT}=13V$			230	μA
Shutdown Current	I_{SHDN}	EN=0			5	μA
FB Leakage Current	I_{FB}		-50		50	nA
Main N-FET RON	$R_{DS(ON)_M}$			9		m Ω
Rectified N-FET RON	$R_{DS(ON)_R}$			12		m Ω
Disconnect N-FET RON	$R_{DS(ON)_D}$			12		m Ω
Main N-FET Current Limit	$I_{LIM,PEAK}$		15		20	A
Switching Frequency	F_{SW}	$R_{FS}=390k\Omega$		345		kHz
Switching Frequency Programmable Range			250		1000	kHz
Feedback Reference Voltage	V_{REF}		0.985	1	1.015	V
IN UVLO Rising Threshold	$V_{IN,UVLO}$				2.85	V
UVLO Hysteresis	$V_{HYS,UVLO}$			0.2		V
EN Rising Threshold	V_{ENH}		1.5			V
EN Falling Threshold	V_{ENL}				0.4	V
Output Current Limit	I_{LIM}	$R_{LIM}=15k\Omega$		1		A
Output Current Limit Programmable Range	$I_{LIM,OUT}$	$V_{OUT} \leq 5V$	1		5	A
		$V_{OUT} > 5V$	1		4	A
Minimum ON Time	$t_{ON,MIN}$			100		ns
Minimum OFF Time	$t_{OFF,MIN}$			120		ns
Error Amplifier Trans-conductance	g_m			100		μS
Current Sense Gain	R_i			75		m Ω
Thermal Shutdown Temperature	T_{SD}			150		$^{\circ}C$
Thermal Shutdown Hysteresis	T_{HYS}			20		$^{\circ}C$

Note 1: Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

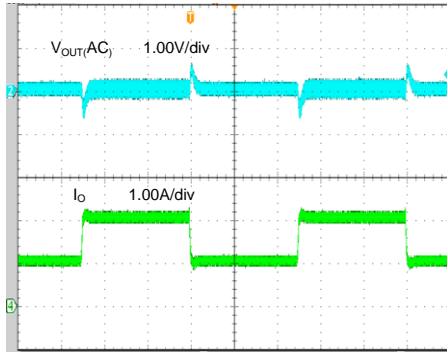
Note 2: θ_{JA} is measured in the natural convection at $T_A = 25^{\circ}C$ on a two-layer Silergy Evaluation Board.

Note 3: The device is not guaranteed to function outside its operating conditions.

Typical Performance Characteristics

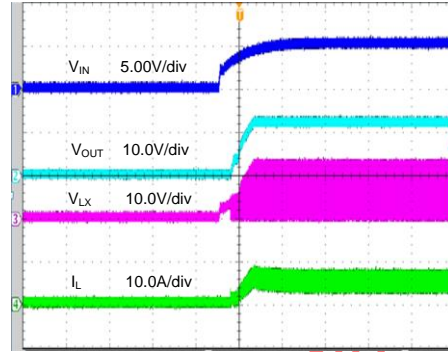


Load Transient
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=1-2A$)



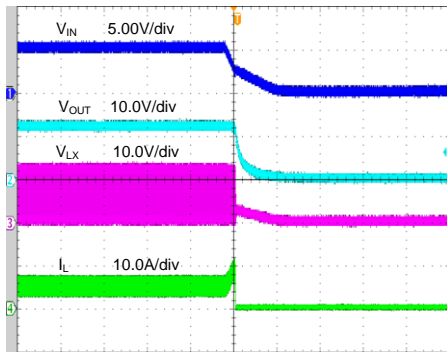
Time (400µs/div)

Startup from V_{IN}
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=2A$)



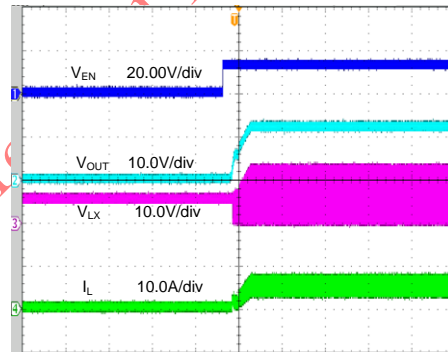
Time (4ms/div)

Shutdown from V_{IN}
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=2A$)



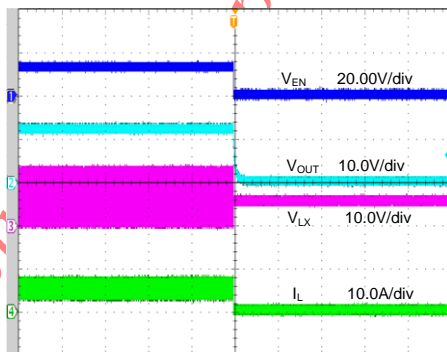
Time (800µs/div)

Startup from Enable
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=2A$)



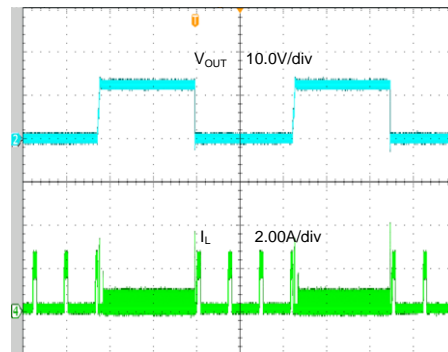
Time (4ms/div)

Shutdown from Enable
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=2A$)



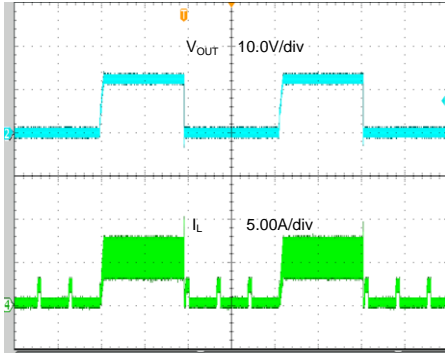
Time (4ms/div)

Short Circuit Protection
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=0A$)



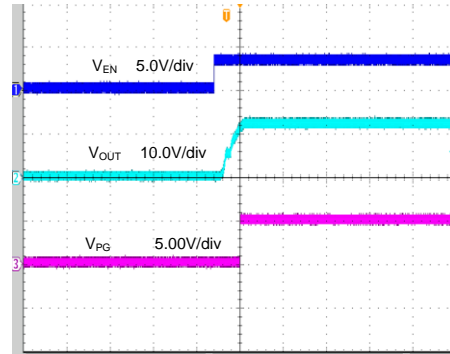
Time (20ms/div)

Short Circuit Protection
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=0A$)



Time (20ms/div)

PG Signal
($V_{IN}=5V$, $V_{OUT}=12V$, $I_{OUT}=2A$)



Time (20ms/div)

Silergy Corp. Confidential Prepared for 

Operation

SY7215A develops a high efficiency synchronous Boost regulator with programmable output current limit. The device adopts adaptive constant off time and current mode control. The integrated low $R_{DS(ON)}$ switches minimize the conduction loss.

SY7215A features cycle by cycle peak current limit, output short circuit protection and true shutdown. The device also provides enable control and power good indicator for system sequence control. Low output voltage ripple and small external inductor and capacitor size are achieved with programmable pseudo-constant frequency.

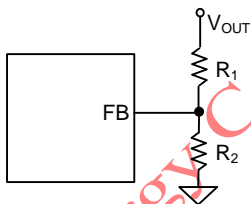
Applications Information

Because of the high integration in SY7215A, the application circuit based on this regulator IC is rather simple. Only the input capacitor C_{IN} , the output capacitor C_{OUT} , the output current limit resistor R_{LIM} , the switching frequency program resistor R_{FS} , the inductor L and the feedback resistors (R_1 and R_2) need to be selected for the targeted applications.

Feedback Resistor Divider R_1 and R_2

Choose R_1 and R_2 to program the proper output voltage. To minimize the power consumption under light load, it is desirable to choose large resistance value for both R_1 and R_2 . A value between 10k and 1M is recommended for both resistors. If $R_1=200k$ is chosen, then R_2 can be calculated to be:

$$R_2 = \frac{R_1}{V_{OUT} - 1} (\Omega)$$



Input Capacitor C_{IN}

The ripple current through input capacitor is calculated as:

$$I_{CIN_RMS} = \frac{V_{IN} \times (V_{OUT} - V_{IN})}{2\sqrt{3} \times L \times F_{SW} \times V_{OUT}} (A)$$

To minimize the potential noise problem, place a typical X5R or better grade ceramic capacitor really close to the VIN and PGND pins. Care should be taken to minimize the loop area formed by C_{IN} , VIN

and PGND pins. In this case, a 10 μ F low ESR ceramic capacitor is recommended.

The SVIN capacitor must be close to the SVIN and SGND pins to minimize the potential noise problem. Care should be taken to minimize the loop area formed by C_{IN1} , SVIN and SGND pins. In this case, a 2 μ F low ESR ceramic is recommended.

Boost Output Capacitor C_{BD} and Disconnection FET Output Capacitor C_{OUT}

The boost output capacitor C_{BD} and disconnection FET output capacitor C_{OUT} are selected to handle the output ripple noise requirement. Both steady state ripple and transient requirements must be taken into account when selecting these capacitors. For the best performance, a X5R or better grade ceramic capacitor with 25V rating and larger than 22 μ F capacitance is recommended.

Boost Inductor L

There are several considerations in choosing this inductor.

- 1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum average input current. The inductance is calculated as:

$$L = \left(\frac{V_{IN}}{V_{OUT}} \right)^2 \frac{(V_{OUT} - V_{IN})}{F_{SW} \times I_{OUT_MAX} \times 40\%} (H)$$

Where F_{SW} is the switching frequency and I_{OUT_MAX} is the maximum load current.

SY7215A is less sensitive to the ripple current variations. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

- 2) The saturation current rating of an inductor must be selected to guarantee an adequate margin to the peak inductor current under full load condition.

$$I_{SAT_MIN} > \left(\frac{V_{OUT}}{V_{IN}} \right) \times I_{OUT_MAX} + \frac{V_{IN}(V_{OUT} - V_{IN})}{2 \times F_{SW} \times L \times V_{OUT}}$$

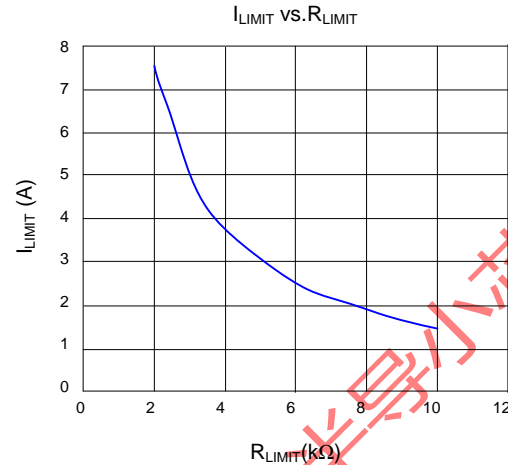
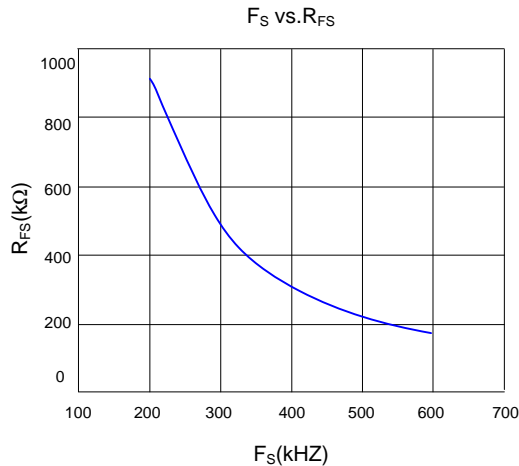
- 3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with $DCR < 10m\Omega$ to achieve a good overall efficiency.

Switch Frequency

The switching frequency of SY7215A in CCM can be programmed by adjusting external resistor R_{FS} connected to FS pin:

$$F_{sw}(\text{kHz}) = 1.4 \times 10^6 / R_{FS}(\Omega)^{0.645}$$

Under light load condition, SY7215A linearly folds back the frequency, thus minimize the output ripple.



Enable Operation

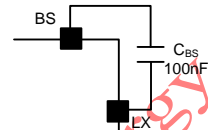
Pulling the EN pin low (<0.4V) will shut down the IC. During shut-down mode, driving the EN pin high (>1.5V) will turn on the IC again.

Power Good Indication

PG is an open-drain output pin. This pin will pull to ground if output voltage is lower than 90% of regulation voltage. Otherwise this pin will go to a high impedance state.

External Bootstrap Cap

This capacitor provides the gate driver voltage for internal rectifier. A 100nF low ESR ceramic capacitor connected between BS pin and LX pin is recommended.



Output Current Limit

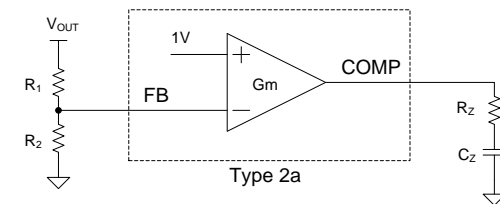
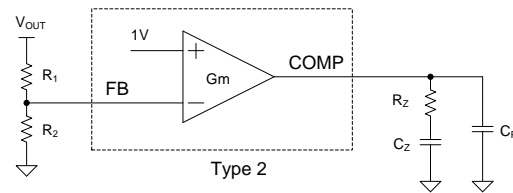
There are two feedback loops inside the regulator. When the voltage on ILIM pin meets 1V threshold, the current feedback loop will take over and regulate the output DC current to the target value.

$$I_{LIM}(\text{A}) = 15(\text{V}) / R_{LIM}(\text{k}\Omega)$$

Loop Compensation

The SY7215A incorporates constant off time current mode control scheme. The current mode control scheme has two feedback loops. The inner loop, current loop, does not require any external compensation component. The outer loop, voltage loop, is compensated with external components.

In most applications, a Type 2 or Type 2a compensation network shown below can be used to stabilize the voltage loop. The Type 2 is the most widely used and works fine for power stages lagging down to -90° and where the boost brought by the output capacitor ESR must be canceled. Type 2a is used where the output capacitor ESR effect can be neglected.



Follow the steps below to calculate the value of external components for voltage loop compensation.

1. Select the crossover frequency f_c of the closed loop. It is recommend that the crossover frequency is

chosen to be the minimum value of 1/5 of right half plane zero (f_{RHPZ}) and 1/10 of switching frequency for the tradeoff of stability and transient response of the system. The system has faster response at higher crossover frequency.

$$f_{RHPZ} = \frac{(1-D_{MAX})^2 \times V_{OUT}}{2\pi \times L \times I_{OUT}}$$

2. Select a R_z value of the R-C series combination connected to the COMP pin.

$$R_z = \frac{V_{OUT}}{g_m \times G_{fc} \times V_{REF}}$$

Where g_m is the error amplifier trans-conductance, which is typically 100uS; G_{fc} is gain of the power stage at crossover frequency.

$$G_{fc} = \frac{(1-D_{MAX})}{2\pi \times fc \times C_{OUT} \times R_i}$$

Where R_i is the current sense gain, which is typically 75mΩ.

3. Select a C_z value of the R-C series combination connected to the COMP pin. The compensation zero decides phase margin at the crossover frequency. Place a compensation zero at or before the dominant pole of R_L and C_O . R_L is the load resistance, which equals to V_{OUT}/I_{OUT} .

$$C_z = \frac{V_{OUT} \times C_{OUT}}{I_{OUT} \times R_z}$$

4. A high frequency pole is recommended to attenuate the high frequency noise. Place this pole to cancel the ESR zero of C_{OUT}

$$C_p = \frac{R_{ESR} \times C_O}{R_z}$$

Layout Design

The layout design of SY7215A is highly simplified. To achieve a higher efficiency and better noise immunity, following components should be placed close to the IC: C_{IN} , C_{BD} , C_{OUT} , L, R_1 and R_2 .

- 1) It is desirable to maximize the PCB copper area connecting to PGND pin to achieve a better thermal performance and noise immunity. If the board space allowed, a designated ground plane layer is highly recommended.
- 2) C_{IN} must be close to SVIN and SGND pins. The loop area formed by C_{BD} , LX and PGND pins must be minimized.
- 3) The PCB copper area associated with LX pin must be minimized to improve the noise immunity.
- 4) The components R_1 and R_2 , and the trace connecting to the FB pin must NOT be adjacent to the LX node on the PCB layout to minimize the noise coupling to FB pin.
- 5) If the system chip interfacing with the EN pin has a high impedance state at shutdown mode and the SVIN pin is connected directly to a power source such as a Li-Ion battery, it is desirable to add a pull down 1MΩ resistor across the EN and SGND pins to prevent the noise from falsely turning on the regulator at shutdown mode.

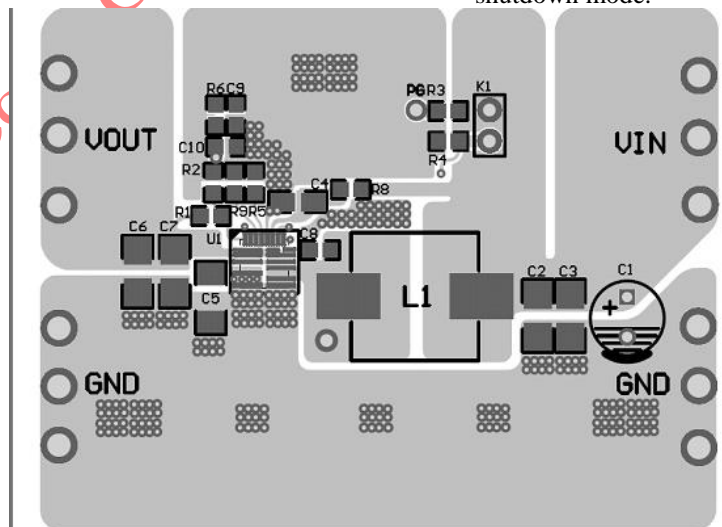
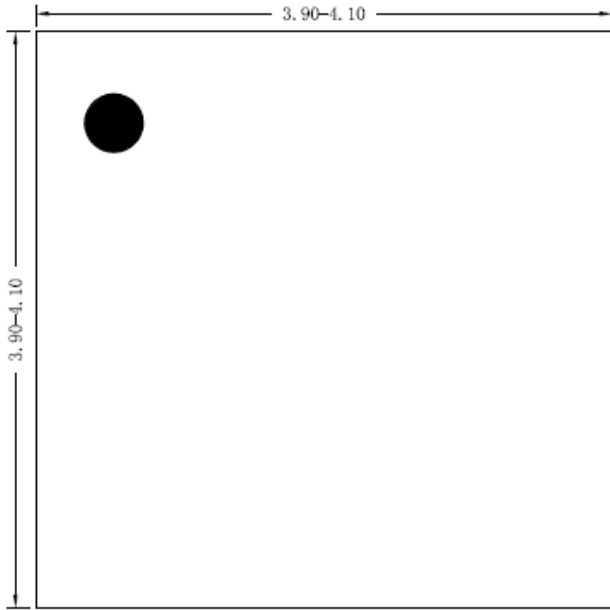
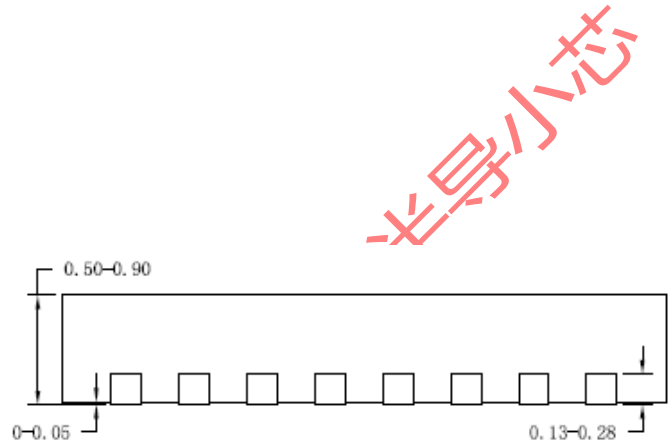


Figure4. PCB Layout Suggestion

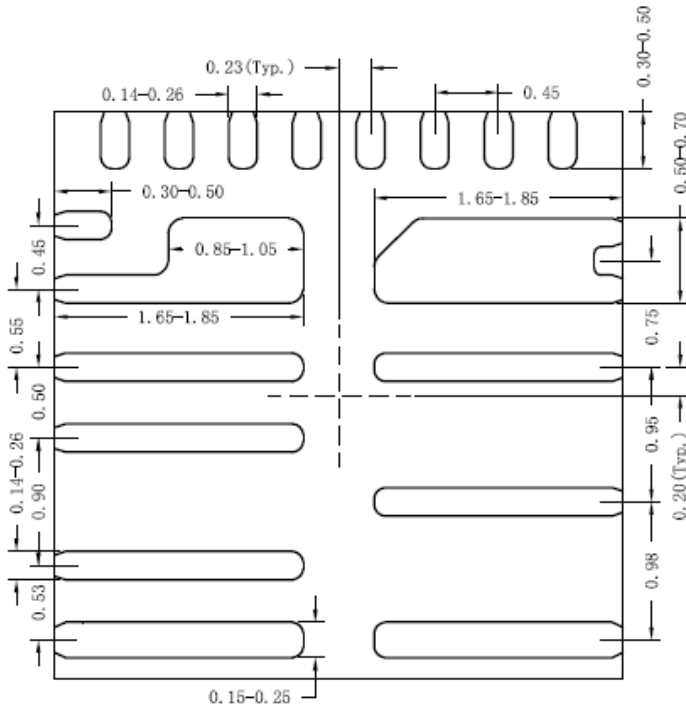
QFN4×4-18 Package Outline & PCB layout design



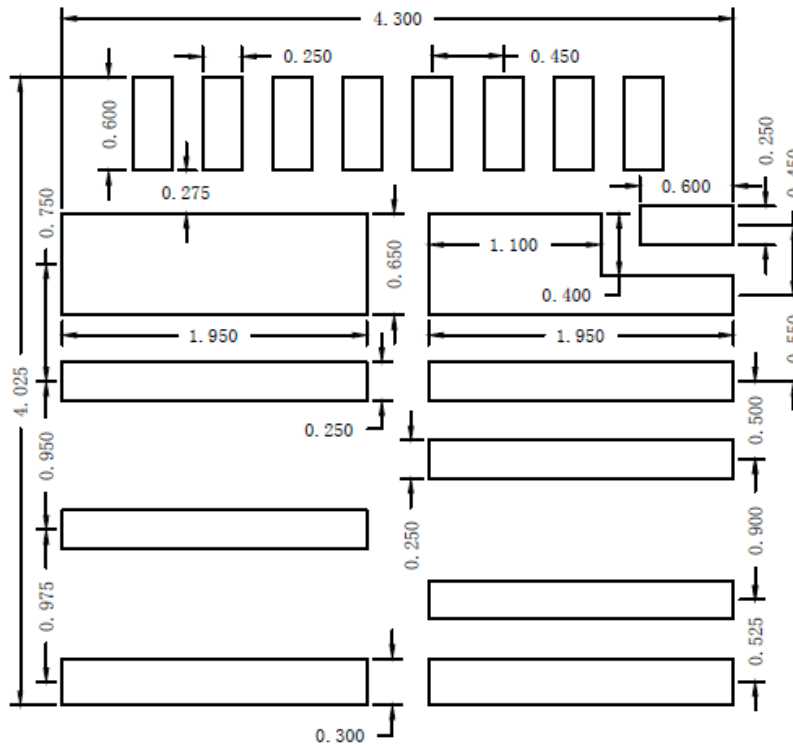
Top View



Side View



Bottom View



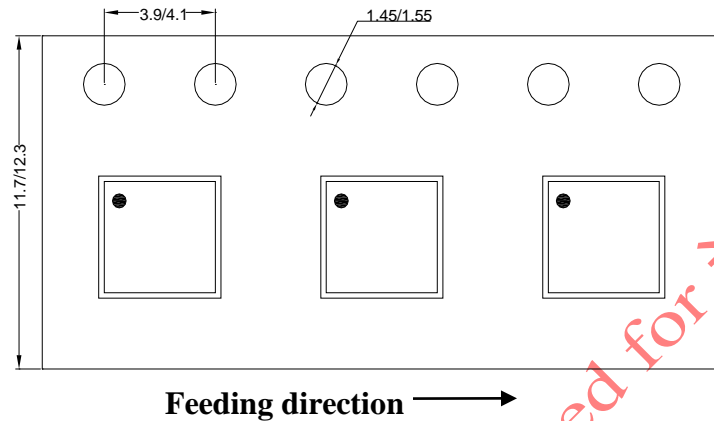
Recommended PCB layout (Reference only)

Notes: All dimension in millimeter and exclude mold flash & metal burr

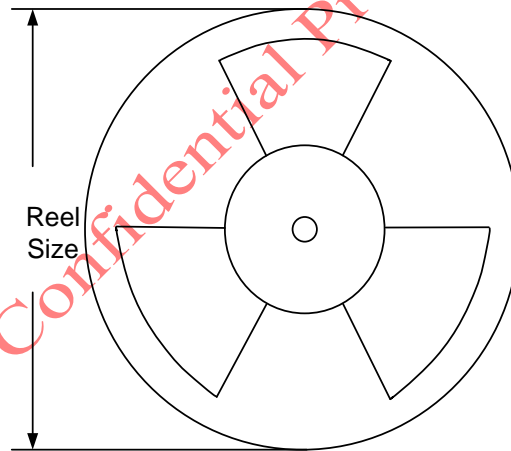
Taping & Reel Specification

1. Taping orientation

QFN4×4



2. Carrier Tape & Reel specification for packages



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
QFN4×4	12	8	13"	400	400	5000

3. Others: NA

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